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# FDB12N50TM

## N-Channel UniFET™ MOSFET

### 500 V, 11.5 A, 650 mΩ



#### Features

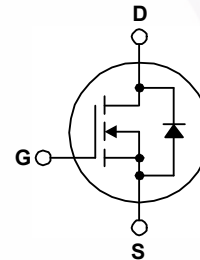
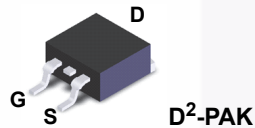
- $R_{DS(on)} = 550 \text{ m}\Omega$  (Typ.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 6 \text{ A}$
- Low Gate Charge (Typ. 22 nC)
- Low  $C_{rss}$  (Typ. 12 pF)
- 100% Avalanche Tested
- RoHS Compliant

#### Applications

- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

#### Description

UniFET™ MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



#### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FDB12N50TM	Unit
$V_{DSS}$	Drain to Source Voltage	500	V
$V_{GSS}$	Gate to Source Voltage	$\pm 30$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	11.5
		- Continuous ( $T_C = 100^\circ\text{C}$ )	6.9
$I_{DM}$	Drain Current	- Pulsed (Note 1)	46
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	456
$I_{AR}$	Avalanche Current	(Note 1)	11.5
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	16.7
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	4.5
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	165
		- Derate above $25^\circ\text{C}$	1.33
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

#### Thermal Characteristics

Symbol	Parameter	FDB12N50TM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.75	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	
	Thermal Resistance, Junction to Ambient (1 in <sup>2</sup> pad of 2 oz copper), Max.	40	

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB12N50	FDB12N50TM	D <sup>2</sup> -PAK	330mm	24mm	800 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	500	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	0.66	-	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 500\text{V}, V_{GS} = 0\text{V}$ $V_{DS} = 400\text{V}, T_C = 125^\circ\text{C}$	-	-	1 10	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 6\text{A}$	-	0.55	0.65	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 25\text{V}, I_D = 6\text{A}$	-	11	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	985	1315	pF
$C_{oss}$	Output Capacitance		-	140	190	pF
$C_{rss}$	Reverse Transfer Capacitance		-	12	17	pF
$Q_g$	Total Gate Charge at 10V	$V_{DS} = 400\text{V}, I_D = 11.5\text{A}$ $V_{GS} = 10\text{V}$	-	22	30	nC
$Q_{gs}$	Gate to Source Gate Charge		-	6	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	10	-	nC

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 250\text{V}, I_D = 11.5\text{A}$ $R_G = 25\Omega$	-	25	60	ns
$t_r$	Turn-On Rise Time		-	60	130	ns
$t_{d(off)}$	Turn-Off Delay Time		-	45	105	ns
$t_f$	Turn-Off Fall Time		-	35	85	ns

### Drain-Source Diode Characteristics

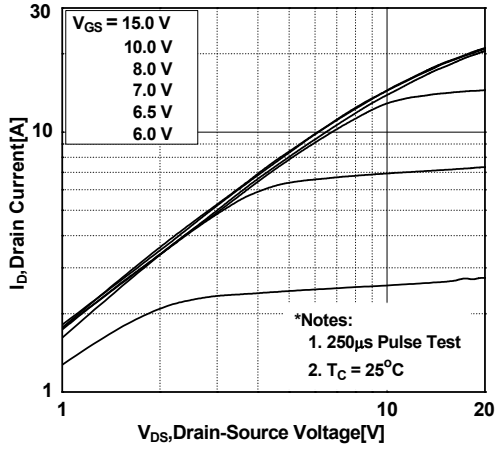
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	11.5	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	46	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 11.5\text{A}$	-	-	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_{SD} = 11.5\text{A}$	-	370	-	ns
$Q_{rr}$	Reverse Recovery Charge	$di_F/dt = 100\text{A}/\mu\text{s}$	-	3.8	-	$\mu\text{C}$

Notes:

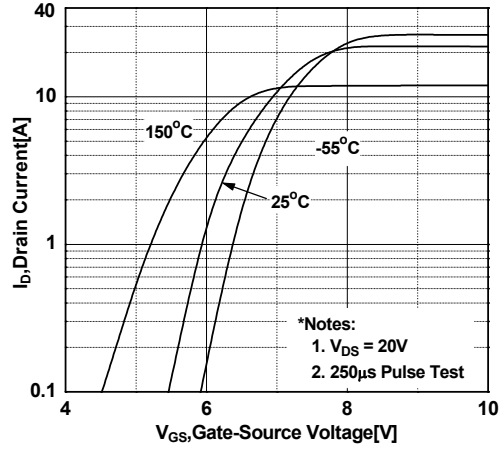
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $L = 6.9\text{mH}, I_{AS} = 11.5\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 11.5\text{A}, di/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Characteristics

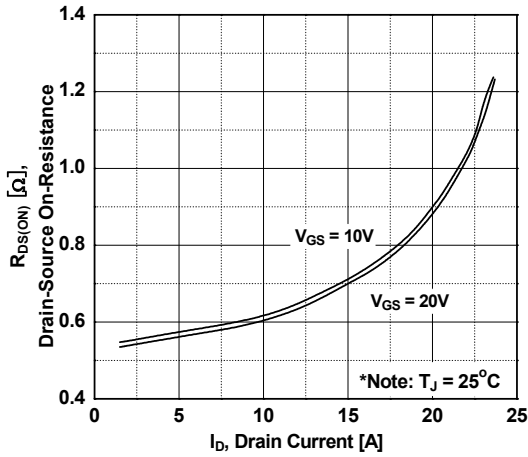
**Figure 1. On-Region Characteristics**



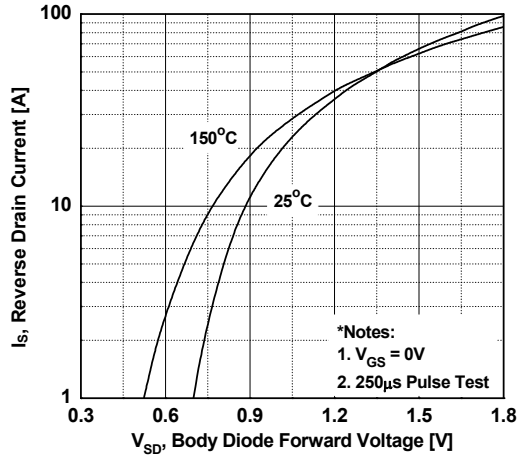
**Figure 2. Transfer Characteristics**



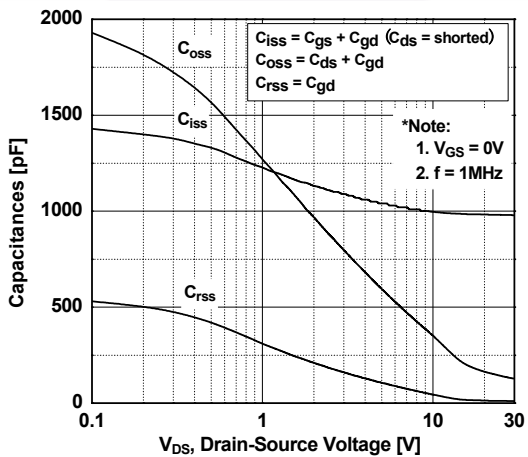
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



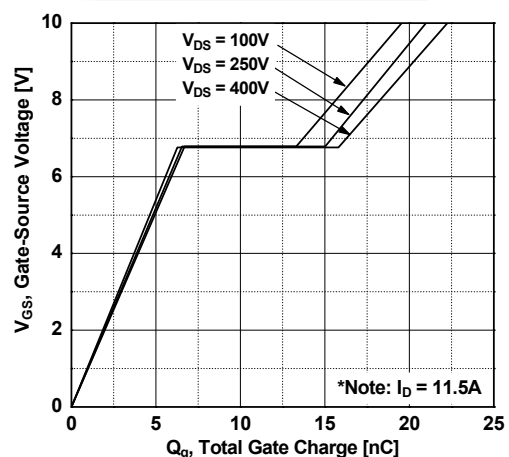
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

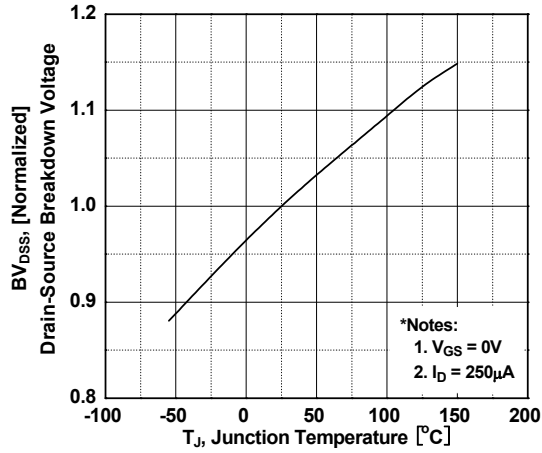


Figure 8. On-Resistance Variation vs. Temperature

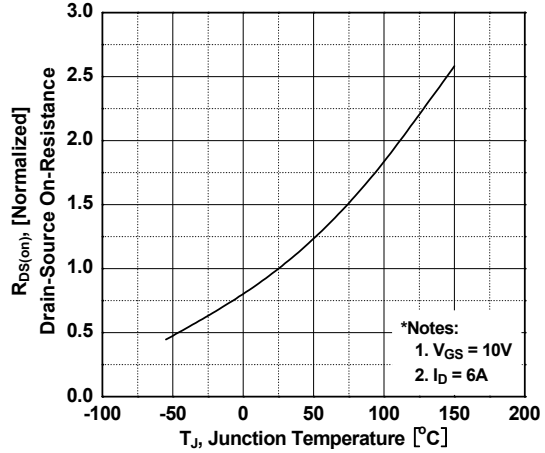


Figure 9. Maximum Safe Operating Area

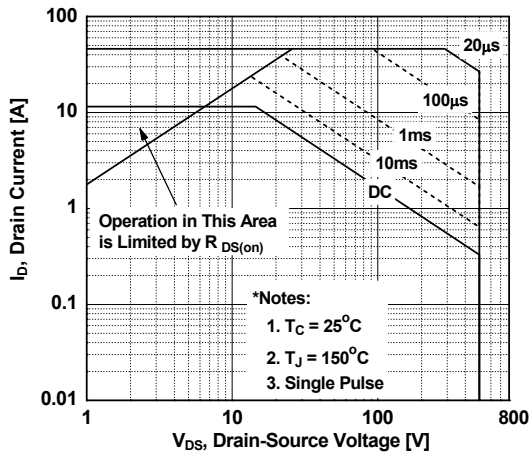


Figure 10. Maximum Drain Current vs. Case Temperature

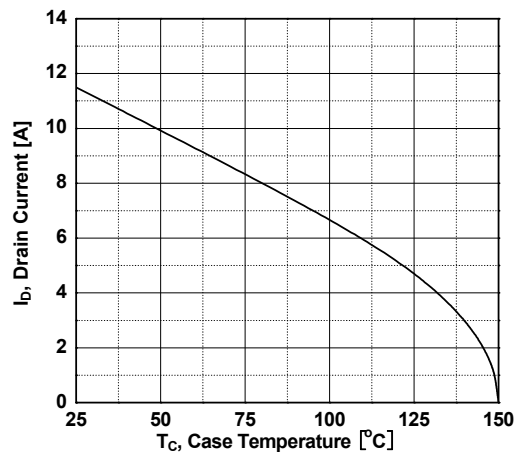
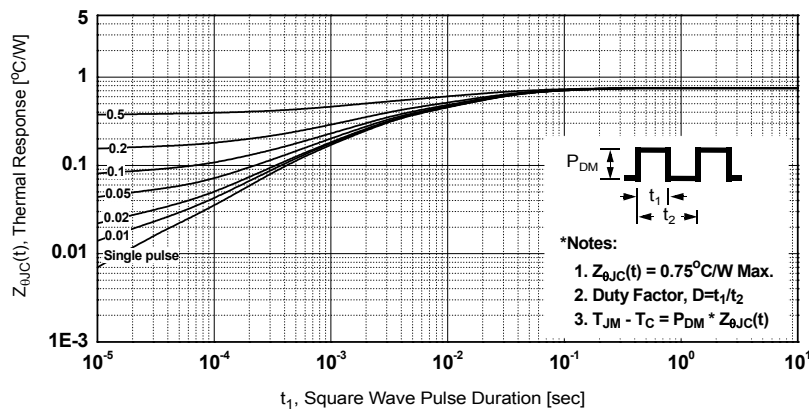
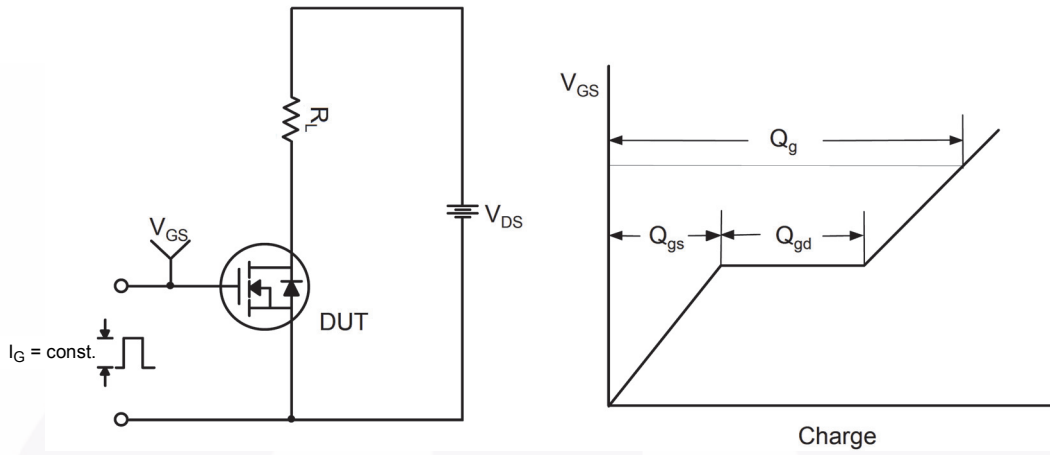


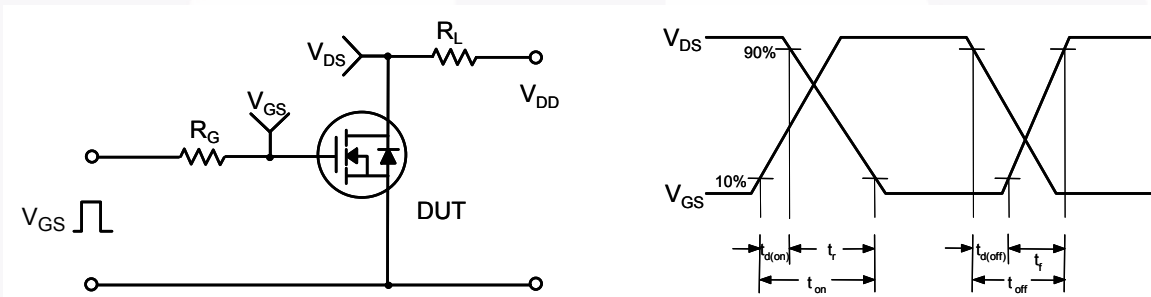
Figure 11. Transient Thermal Response Curve



**Figure 12. Gate Charge Test Circuit & Waveform**



**Figure 13. Resistive Switching Test Circuit & Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

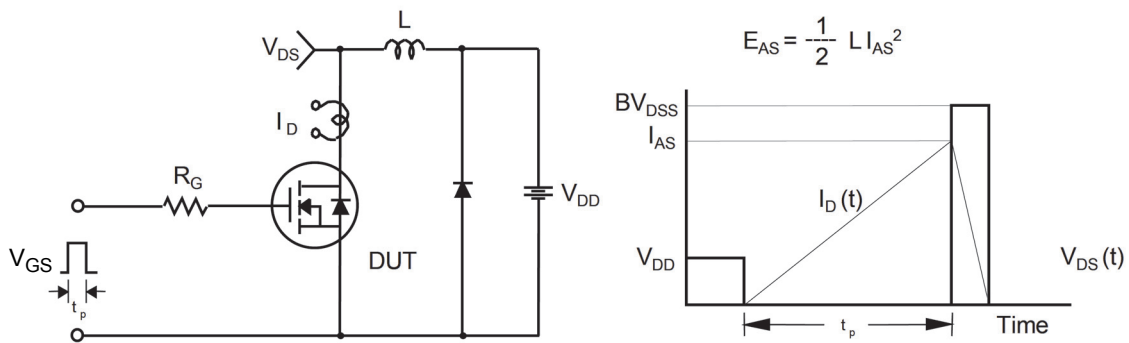
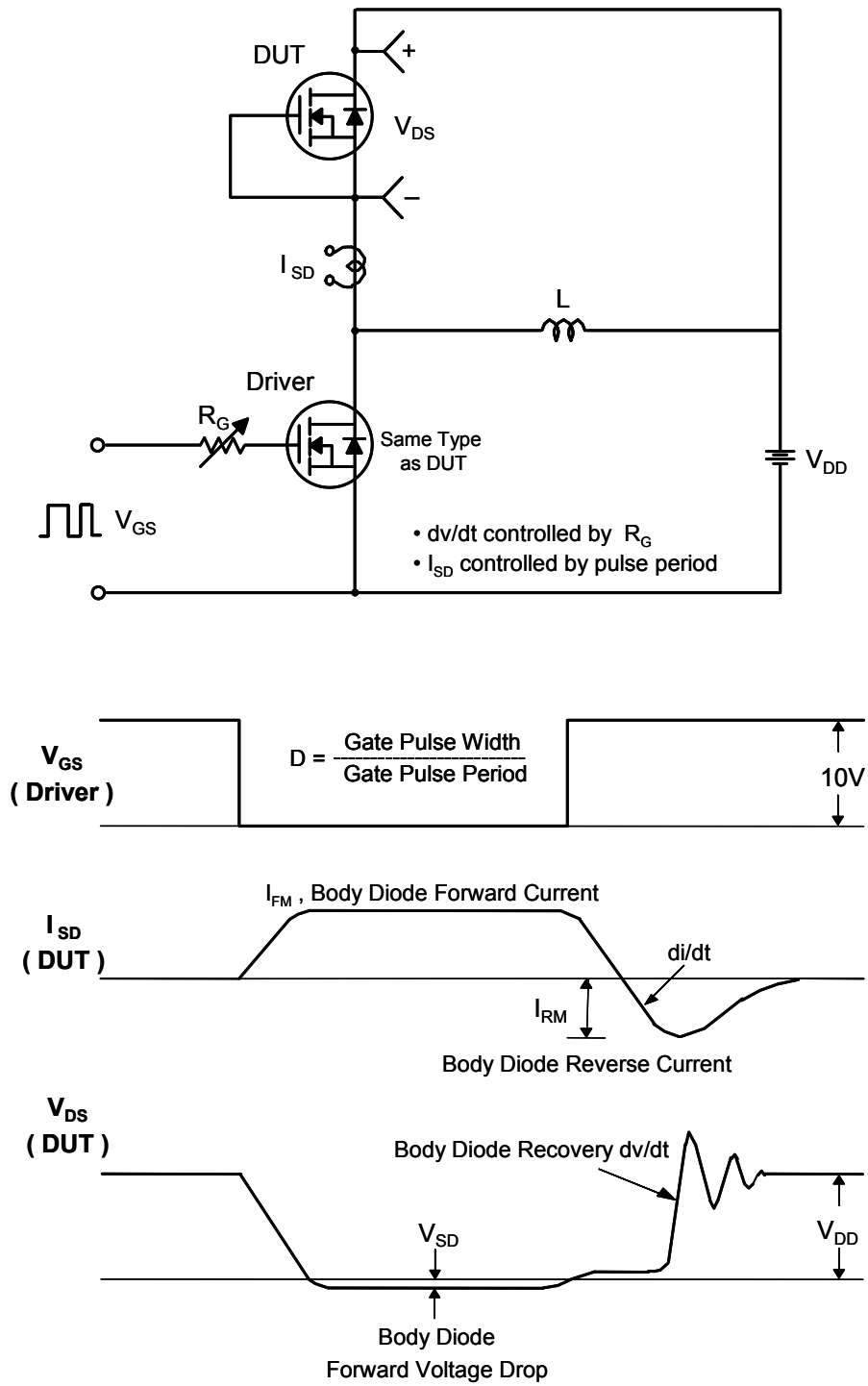
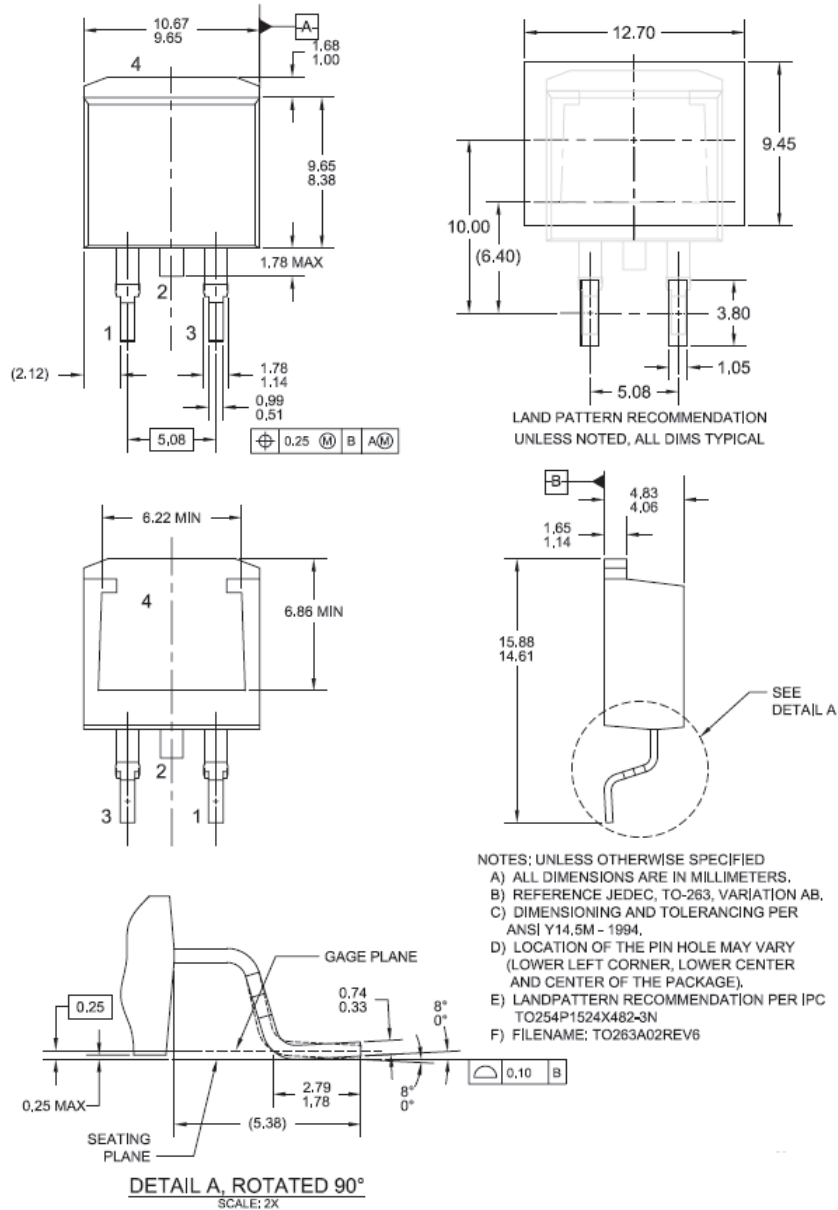


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



**Mechanical Dimensions**

**TO-263 2L (D<sup>2</sup>PAK)**



**Figure 16. 2LD, TO263, Surface Mount**

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Dimension in Millimeters





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